



#### **General Description**

The MAX4411 fixed-gain, stereo headphone amplifier is designed for portable equipment where board space is at a premium. The MAX4411 uses a unique DirectDrive architecture to produce a ground-referenced output from a single supply, eliminating the need for large DCblocking capacitors, saving cost, board space, and component height. Additionally, the gain of the amplifier is set internally (-1.5V/V, MAX4411 and -2V/V, MAX4411B), further reducing component count.

The MAX4411 delivers up to 80mW per channel into a  $16\Omega$  load and has low 0.003% THD+N. An 86dB at 217Hz power-supply rejection ratio (PSRR) allows this device to operate from noisy digital supplies without an additional linear regulator. The MAX4411 includes ±8kV ESD protection on the headphone outputs. Comprehensive click-and-pop circuitry suppresses audible clicks and pops on startup and shutdown. Independent left/right, low-power shutdown controls make it possible to optimize power savings in mixed-mode, mono/stereo applications.

The MAX4411 operates from a single 1.8V to 3.6V supply, consumes only 5mA of supply current, has short-circuit and thermal-overload protection, and is specified over the extended -40°C to +85°C temperature range. The MAX4411 is available in a tiny  $(2mm \times 2mm \times 0.6mm)$ , 16-bump chip-scale package (UCSP™) and a 20-pin thin QFN package (4mm  $\times$  4mm  $\times$  0.8mm).

#### Applications

MP3 Players Notebook PCs Cellular Phones **Smart Phones** 

**PDAs** Portable Audio Equipment

UCSP is a trademark of Maxim Integrated Products, Inc.

#### Features

- ♦ No Bulky DC-Blocking Capacitors Required
- ♦ Fixed -1.5V/V Gain Eliminates External Feedback Network

MAX4411: -1.5V/V MAX4411B: -2V/V

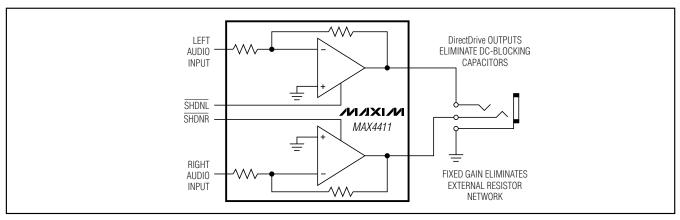
- ♦ Ground-Referenced Outputs Eliminate DC-Bias Voltages on Headphone Ground Pin
- ♦ No Degradation of Low-Frequency Response Due to Output Capacitors
- ♦ 80mW per Channel into 16Ω
- ♦ Low 0.003% THD+N
- ♦ High PSRR (86dB at 217Hz)
- **♦ Integrated Click-and-Pop Suppression**
- ♦ 1.8V to 3.6V Single-Supply Operation
- **♦ Low Quiescent Current (5mA)**
- ♦ Independent Left/Right, Low-Power **Shutdown Controls**
- ♦ Short-Circuit and Thermal-Overload Protection
- ♦ ±8kV ESD-Protected Amplifier Outputs
- **♦** Available in Space-Saving Packages 16-Bump UCSP (2mm  $\times$  2mm  $\times$  0.6mm) 20-Pin Thin QFN (4mm  $\times$  4mm  $\times$  0.8mm)

### **Ordering Information**

PART	TEMP RANGE	PIN/BUMP- PACKAGE	GAIN (V/V)
MAX4411EBE-T	-40°C to +85°C	16 UCSP-16	-1.5
MAX4411EBE+T	-40°C to +85°C	16 UCSP-16	-1.5
MAX4411ETP	-40°C to +85°C	20 Thin QFN	-1.5

Ordering Information continued at end of data sheet.

## **Functional Diagram**



Pin Configurations and Typical Application Circuit appear at end of data sheet.

MIXIM

Maxim Integrated Products 1

<sup>+</sup>Denotes lead-free package.

#### **ABSOLUTE MAXIMUM RATINGS**

PGND to SGND		0.3V to +0.3V
PV <sub>DD</sub> to SV <sub>DD</sub>		-0.3V to +0.3V
PVss to SVss		0.3V to +0.3V
PV <sub>DD</sub> and SV <sub>DD</sub> to PGNI	D or SGND	0.3V to +4V
PVSS and SVSS to PGND	or SGND	4V to +0.3V
IN_ to SGND	(SV <sub>SS</sub> -	$0.3V$ ) to $(SV_{DD} + 0.3V)$
SHDN_ to SGND	(SGND -	$0.3V$ ) to $(SV_{DD} + 0.3V)$
OUT_ to SGND	(SV <sub>SS</sub>	- 0.3V) to (SV <sub>DD</sub> +0.3V)
C1P to PGND	`	, , ,
C1N to PGND	(PVss -	0.3V) to (PGND + 0.3V)

Output Short Circuit to GND or VDDContinuous
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )
16-Bump UCSP (derate 7.4mW/°C above +70°C)589mW
20-Pin Thin QFN (derate 16.9mW/°C above +70°C)1349mW
Junction Temperature+150°C
Operating Temperature Range40°C to +85°C
Storage Temperature Range65°C to +150°C
Bump Temperature (soldering)
Reflow+230°C
Lead Temperature (soldering, 10s)+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(PV_{DD} = SV_{DD} = 3V, PGND = SGND = 0V, \overline{SHDNL} = \overline{SHDNR} = SV_{DD}, C1 = C2 = 2.2\mu F, C_{IN} = 1\mu F, R_{L} = \infty, T_{A} = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_{A} = +25^{\circ}C$ .) (Note 1)

PARAMETER	SYMBOL	CONDIT	IONS	MIN	TYP	MAX	UNITS
Supply Voltage Range	$V_{DD}$	Guaranteed by PSRR te	st	1.8		3.6	V
Out and the Comment		One channel enabled			3.2		^
Quiescent Supply Current	IDD	Two channels enabled			5	8.4	mA
Shutdown Supply Current	ISHDN	SHDNL = SHDNR = GN	D		6	10	μΑ
CLIDAL Thresholds		VIH		0.7 x SV <sub>DD</sub>			V
SHDN_ Thresholds		V <sub>IL</sub>				0.3 x SV <sub>DD</sub>	V
SHDN_ Input Leakage Current				-1		+1	μΑ
SHDN_ to Full Operation	tson				175		μs
CHARGE PUMP							
Oscillator Frequency	fosc			272	320	368	kHz
AMPLIFIERS							
Voltage Gain	Av	MAX4411		-1.55	-1.5	-1.45	V/V
Voltage Gaiii	Av	MAX4411B		-2.1	-2	-1.9	V/V
Gain Match	ΔΑγ				1		%
Total Output Offact Voltage	\/00	Input AC coupled	MAX4411		0.7	2.8	mV
Total Output Offset Voltage	Vos	Input AC-coupled	MAX4411B		0.75	3.0	IIIV
Input Resistance	RIN			10	14	19	kΩ
		$1.8V \le V_{DD} \le 3.6V$ , MAX4411	DC (Note 2)	72	86		
Power-Supply Rejection Ratio	PSRR	$V_{DD} = 3.0V, 200 \text{mV}_{P-P}$	f <sub>RIPPLE</sub> = 217Hz		86		dB
		ripple, MAX4411	f <sub>RIPPLE</sub> = 1kHz		75	·	
		(Note 3)	$f_{RIPPLE} = 20kHz$		53		

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(PV_{DD} = SV_{DD} = 3V, PGND = SGND = 0V, \overline{SHDNL} = \overline{SHDNR} = SV_{DD}, C1 = C2 = 2.2\mu F, C_{IN} = 1\mu F, R_L = \infty, T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 1)

PARAMETER	SYMBOL	CONDIT	IONS	MIN	TYP	MAX	UNITS
		$1.8V \le V_{DD} \le 3.6V$ , MAX4411B	DC (Note 2)	69	86		
Power-Supply Rejection Ratio	PSRR	$V_{DD} = 3.0V, 200 \text{mV}_{P-P}$	f <sub>RIPPLE</sub> = 217Hz		86		dB
		ripple, MAX4411B	f <sub>RIPPLE</sub> = 1kHz		73		
		(Note 3)	f <sub>RIPPLE</sub> = 20kHz		51		
Output Power	Do. IT	THD+N≤1%	$R_L = 32\Omega$		65		mW
Output Fower	Pout	$T_A = +25^{\circ}C$	$R_L = 16\Omega$	55	80		IIIVV
Total Harmonic Distortion Plus	TUD. N	£ 41.11=	$R_L = 32\Omega$ , $P_{OUT} = 50$ mW		0.003		%
Noise	THD+N	$f_{IN} = 1kHz$	$R_L = 16\Omega$ , $P_{OUT} = 60$ mW		0.004		%
Signal-to-Noise Ratio	SNR	$R_L = 32\Omega$ , $P_{OUT} = 20$ mW, $f_{IN} = 1$ kHz,	MAX4411		94		dB
Signal-to-Noise Hatio	SINIT	BW = 22Hz  to  22kHz	MAX4411B		95		uБ
Slew Rate	SR				0.8		V/µs
Maximum Capacitive Load	CL	No sustained oscillations	S		150		рF
Crosstalk		$R_L = 16\Omega$ , $P_{OUT} = 1.6$ m	W, f <sub>IN</sub> = 10kHz		90		dB
Thermal Shutdown Threshold					140		°C
Thermal Shutdown Hysteresis					15		°C
ESD Protection		Human Body Model (OL	JTR, OUTL)		±8		kV

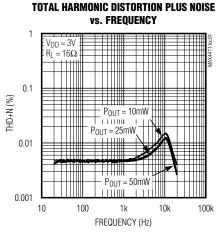
**Note 1:** All specifications are 100% tested at  $T_A = +25^{\circ}C$ ; temperature limits are guaranteed by design.

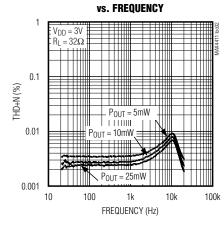
Note 2: Inputs are connected directly to GND.

Note 3: Inputs are AC-coupled to ground.

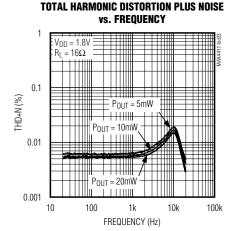
## Typical Operating Characteristics

(C1 = C2 = 2.2µF, THD+N measurement bandwidth = 22Hz to 22kHz, TA = +25°C, unless otherwise noted.)





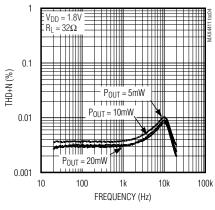
**TOTAL HARMONIC DISTORTION PLUS NOISE** 



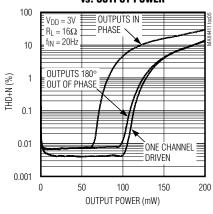
#### Typical Operating Characteristics (continued)

(C1 = C2 =  $2.2\mu$ F, THD+N measurement bandwidth = 22Hz to 22kHz,  $T_A = +25$ °C, unless otherwise noted.)

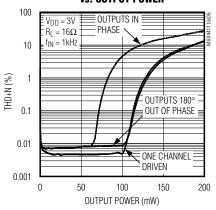
## TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY



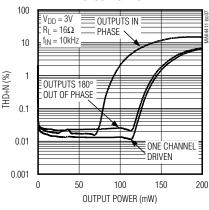
TOTAL HARMONIC DISTORTION PLUS NOISE vs. Output Power



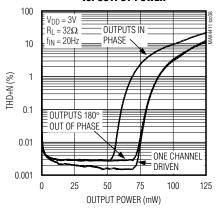
TOTAL HARMONIC DISTORTION PLUS NOISE vs. Output power



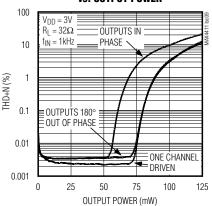
TOTAL HARMONIC DISTORTION PLUS NOISE vs. Output Power



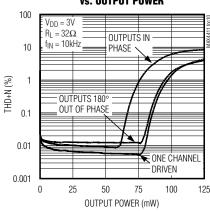
TOTAL HARMONIC DISTORTION PLUS NOISE vs. Output Power



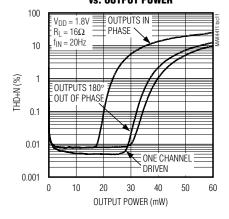
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER



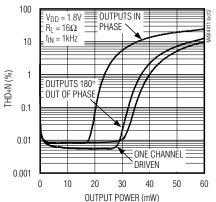
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER



TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER

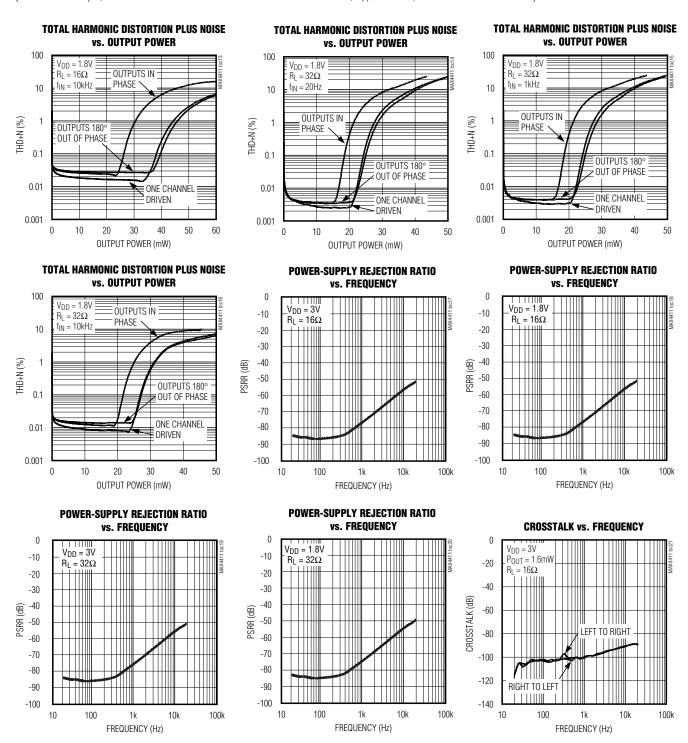


TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER



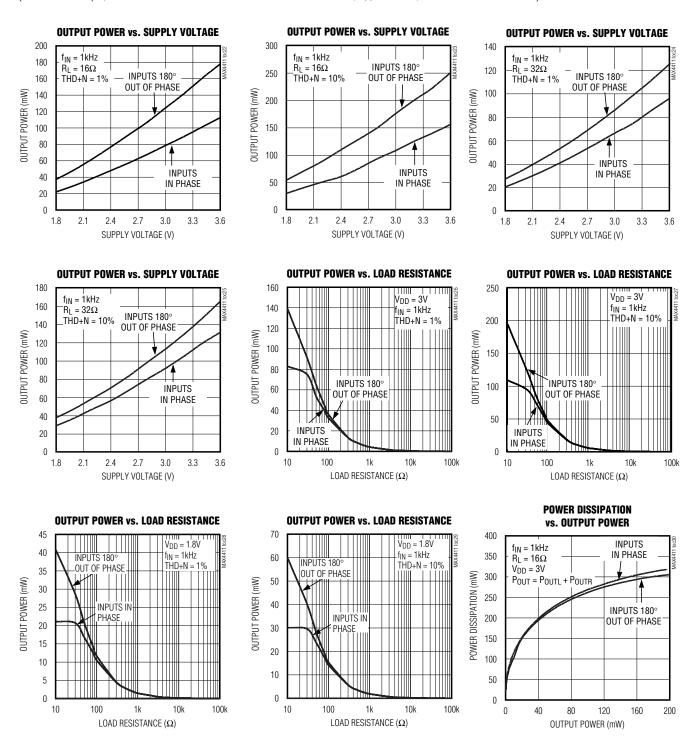
### Typical Operating Characteristics (continued)

(C1 = C2 = 2.2µF, THD+N measurement bandwidth = 22Hz to 22kHz, T<sub>A</sub> = +25°C, unless otherwise noted.)



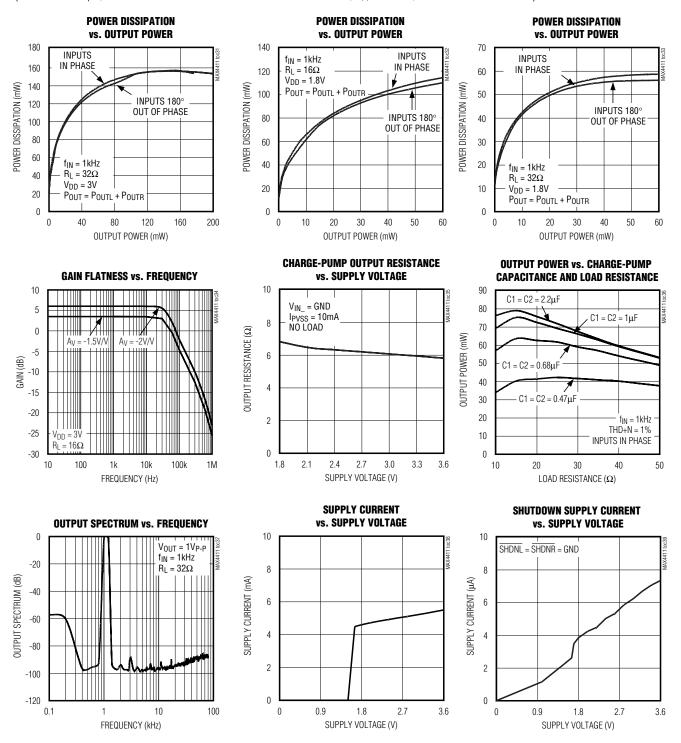
### Typical Operating Characteristics (continued)

(C1 = C2 = 2.2µF, THD+N measurement bandwidth = 22Hz to 22kHz, T<sub>A</sub> = +25°C, unless otherwise noted.)



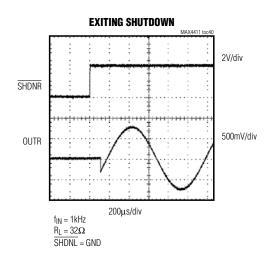
### Typical Operating Characteristics (continued)

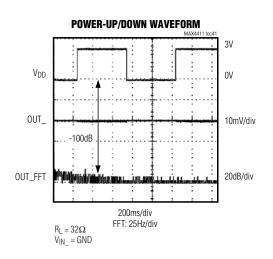
(C1 = C2 = 2.2µF, THD+N measurement bandwidth = 22Hz to 22kHz, T<sub>A</sub> = +25°C, unless otherwise noted.)



## Typical Operating Characteristics (continued)

(C1 = C2 = 2.2µF, THD+N measurement bandwidth = 22Hz to 22kHz, T<sub>A</sub> = +25°C, unless otherwise noted.)





## Pin Description

PIN	BUMP	NAME	FUNCTION
QFN	UCSP	NAME	FUNCTION
1	A4	C1P	Flying Capacitor Positive Terminal
2	B4	PGND	Power Ground. Connect to ground (0V).
3	C4	C1N	Flying Capacitor Negative Terminal
4, 6, 8, 12, 16, 20	_	N.C.	No Connection. Not internally connected.
5	D4	PV <sub>SS</sub>	Charge-Pump Output
7	D3	SV <sub>SS</sub>	Amplifier Negative Power Supply. Connect to PVSS.
9	D2	OUTL	Left-Channel Output
10	D1	SV <sub>DD</sub>	Amplifier Positive Power Supply. Connect to positive supply (1.8V to 3.6V).
11	C2	OUTR	Right-Channel Output
13	C1	INL	Left-Channel Audio Input
14	B1	SHDNR	Active-Low Right-Channel Shutdown. Connect to VDD for normal operation.
15	A1	INR	Right-Channel Audio Input
17	A2	SGND	Signal Ground. Connect to ground (0V).
18	B2	SHDNL	Active-Low Left-Channel Shutdown. Connect to V <sub>DD</sub> for normal operation.
19	А3	PV <sub>DD</sub>	Charge-Pump Power Supply. Powers charge-pump inverter, charge-pump logic, and oscillator. Connect to positive supply (1.8V to 3.6V).
_	_	EP	Exposed Paddle. Leave unconnected. Do not connect to any voltage including GND or V <sub>DD</sub> .

#### **Detailed Description**

The MAX4411 fixed-gain, stereo headphone driver features Maxim's DirectDrive architecture, eliminating the large output-coupling capacitors required by conventional single-supply headphone drivers. The device consists of two 80mW Class AB headphone drivers, internal feedback network, undervoltage lockout (UVLO)/shutdown control, charge pump, and comprehensive clickand-pop suppression circuitry (see Typical Application Circuit). The charge pump inverts the positive supply (PVDD), creating a negative supply (PVSS). The headphone drivers operate from these bipolar supplies with their outputs biased about GND (Figure 1). The drivers have almost twice the supply range compared to other 3V single-supply drivers, increasing the available output power. The benefit of this GND bias is that the driver outputs do not have a DC component typically VDD/2. The large DC-blocking capacitors required with conventional headphone drivers are unnecessary, thus conserving board space, system cost, and improving frequency response.

Each channel has independent left/right, active-low shutdown controls, optimizing power savings in mixed-mode, mono/stereo operation. The device features an undervoltage lockout that prevents operation from an insufficient power supply and click-and-pop suppression that eliminates audible transients on startup and shutdown. Additionally, the MAX4411 features thermal-overload and short-circuit protection and can withstand ±8kV ESD strikes on the output pins.

#### Fixed Gain

The MAX4411 utilizes an internally fixed gain configuration of either -1.5V/V (MAX4411) or -2V/V (MAX4411B). All gain-setting resistors are integrated into the device, reducing external component count. The internally set gain, in combination with DirectDrive, results in a headphone amplifier that requires only five tiny 1µF capacitors to complete the amplifier circuit: two for the charge pump, two for audio input coupling, and one for power-supply bypassing (see *Typical Application Circuit*).

#### **DirectDrive**

Conventional single-supply headphone drivers have their outputs biased about a nominal DC voltage (typically half the supply) for maximum dynamic range. Large coupling capacitors are needed to block this DC bias from the headphone. Without these capacitors, a significant amount of DC current flows to the headphone, resulting in unnecessary power dissipation and possible damage to both headphone and headphone driver.

Maxim's DirectDrive architecture uses a charge pump to create an internal negative supply voltage.

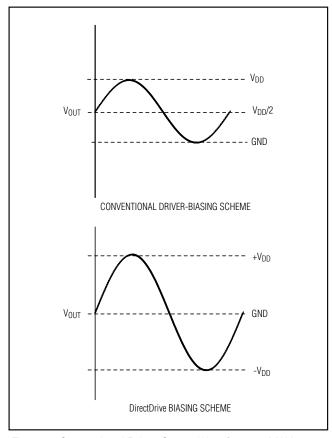


Figure 1. Conventional Driver Output Waveform vs. MAX4411 Output Waveform

This allows the MAX4411 outputs to be biased about GND, almost doubling dynamic range while operating from a single supply. With no DC component, there is no need for the large DC-blocking capacitors. Instead of two large (220µF, typ) tantalum capacitors, the MAX4411 charge pump requires two small ceramic capacitors, conserving board space, reducing cost, and improving the frequency response of the headphone driver. See the Output Power vs. Charge-Pump Capacitance and Load Resistance graph in the Typical Operating Characteristics for details of the possible capacitor sizes. There is a low DC voltage on the driver outputs due to amplifier offset. However, the offset of the MAX4411 is typically 0.7mV, which, when combined with a  $32\Omega$  load, results in less than  $23\mu A$  of DC current flow to the headphones.

Previous attempts to eliminate the output-coupling capacitors involved biasing the headphone return (sleeve) to the DC-bias voltage of the headphone amplifiers. This

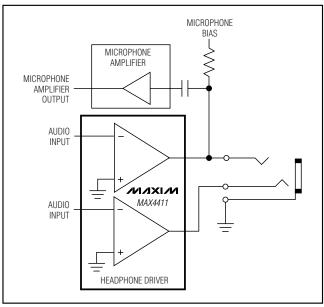
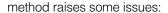


Figure 2. Earbud Speaker/Microphone Combination Headset Configuration



- The sleeve is typically grounded to the chassis.
  Using this biasing approach, the sleeve must be
  isolated from system ground, complicating product
  design.
- During an ESD strike, the driver's ESD structures are the only path to system ground. Thus, the driver must be able to withstand the full ESD strike.
- When using the headphone jack as a line out to other equipment, the bias voltage on the sleeve may conflict with the ground potential from other equipment, resulting in possible damage to the drivers.
- When using a combination microphone and speaker headset, the microphone typically requires a GND reference. The driver DC bias on the sleeve conflicts with the microphone requirements (Figure 2).

#### Low-Frequency Response

In addition to the cost and size disadvantages of the DCblocking capacitors required by conventional headphone amplifiers, these capacitors limit the amplifier's low-frequency response and can distort the audio signal:

 The impedance of the headphone load and the DCblocking capacitor forms a highpass filter with the -3dB point set by:

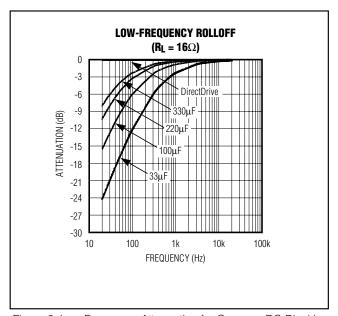


Figure 3. Low-Frequency Attenuation for Common DC-Blocking Capacitor Values

$$f_{-3dB} = \frac{1}{2\pi R_L C_{OUT}}$$

where  $R_{L}$  is the impedance of the headphone and  $C_{OUT}$  is the value of the DC-blocking capacitor.

The highpass filter is required by conventional single-ended, single power-supply headphone drivers to block the midrail DC-bias component of the audio signal from the headphones. The drawback to the filter is that it can attenuate low-frequency signals. Larger values of COUT reduce this effect but result in physically larger, more expensive capacitors. Figure 3 shows the relationship between the size of COUT and the resulting low-frequency attenuation. Note that the -3dB point for a  $16\Omega$  headphone with a  $100\mu\text{F}$  blocking capacitor is 100Hz, well within the normal audio band, resulting in low-frequency attenuation of the reproduced signal.

2) The voltage coefficient of the DC-blocking capacitor contributes distortion to the reproduced audio signal as the capacitance value varies as the function of the voltage across the capacitor changes. At low frequencies, the reactance of the capacitor dominates at frequencies below the -3dB point and the voltage coefficient appears as frequency-dependent distortion. Figure 4 shows the THD+N intro-

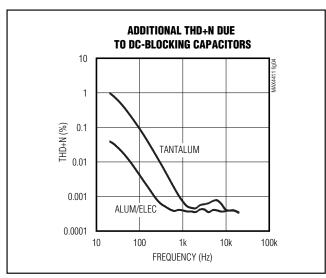


Figure 4. Distortion Contributed by DC-Blocking Capacitors

duced by two different capacitor dielectric types. Note that below 100Hz, THD+N increases rapidly.

The combination of low-frequency attenuation and frequency-dependent distortion compromises audio reproduction in portable audio equipment that emphasizes low-frequency effects such as multimedia laptops, as well as MP3, CD, and DVD players. By eliminating the DC-blocking capacitors through DirectDrive technology, these capacitor-related deficiencies are eliminated.

#### Charge Pump

The MAX4411 features a low-noise charge pump. The 320kHz switching frequency is well beyond the audio range, and thus does not interfere with the audio signals. The switch drivers feature a controlled switching speed that minimizes noise generated by turn-on and turn-off transients. By limiting the switching speed of the charge pump, the di/dt noise caused by the parasitic bond wire and trace inductance is minimized. Although not typically required, additional high-frequency noise attenuation can be achieved by increasing the size of C2 (see *Typical Application Circuit*).

#### Shutdown

The MAX4411 features two shutdown controls allowing either channel to be shut down or muted independently. SHDNL controls the left channel while SHDNR controls the right channel. Driving either SHDN\_ low disables the respective channel, sets the driver output impedance to  $1k\Omega$ , and reduces the supply current. When both SHDN\_ inputs are driven low, the charge pump is also disabled, further reducing supply current draw to

6µA. The charge pump is enabled once either SHDN\_input is driven high.

#### Click-and-Pop Suppression

In conventional single-supply audio drivers, the output-coupling capacitor is a major contributor of audible clicks and pops. Upon startup, the driver charges the coupling capacitor to its bias voltage, typically half the supply. Likewise, on shutdown, the capacitor is discharged to GND. This results in a DC shift across the capacitor, which in turn, appears as an audible transient at the speaker. Since the MAX4411 does not require output-coupling capacitors, this does not arise.

Additionally, the MAX4411 features extensive click-andpop suppression that eliminates any audible transient sources internal to the device. The Power-Up/Down Waveform in the *Typical Operating Characteristics* shows that there are minimal spectral components in the audible range at the output upon startup or shutdown.

In most applications, the output of the preamplifier driving the MAX4411 has a DC bias of typically half the supply. At startup, the input-coupling capacitor is charged to the preamplifier's DC-bias voltage through the RF of the MAX4411, resulting in a DC shift across the capacitor and an audible click/pop. Delaying the rise of the  $\overline{SHDN}_-$  signals 4 to 5 time constants (80ms to 100ms) based on RIN and CIN, relative to the startup of the preamplifier, eliminates this click/pop caused by the input filter.

## Applications Information

#### **Power Dissipation**

Under normal operating conditions, linear power amplifiers can dissipate a significant amount of power. The maximum power dissipation for each package is given in the *Absolute Maximum Ratings* section under Continuous Power Dissipation or can be calculated by the following equation:

$$P_{DISSPKG(MAX)} = \frac{T_{J(MAX)} - T_{A}}{\theta_{JA}}$$

where  $T_{J(MAX)}$  is +150°C,  $T_A$  is the ambient temperature, and  $\theta_{JA}$  is the reciprocal of the derating factor in °C/W as specified in the *Absolute Maximum Ratings* section. For example,  $\theta_{JA}$  of the QFN package is +59.3°C/W.

The MAX4411 has two power dissipation sources, the charge pump and the two drivers. If the power dissipation for a given application exceeds the maximum allowed for a given package, either reduce V<sub>DD</sub>, increase load impedance, decrease the ambient temperature, or add heatsinking to the device. Large

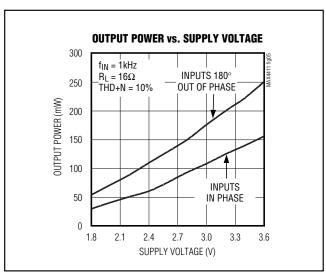


Figure 5. Output Power vs. Supply Voltage with Inputs In/Out of Phase

output, supply, and ground traces improve the maximum power dissipation in the package.

Thermal-overload protection limits total power dissipation in the MAX4411. When the junction temperature exceeds +140°C, the thermal protection circuitry disables the amplifier output stage. The amplifiers are enabled once the junction temperature cools by 15°C. This results in a pulsing output under continuous thermal-overload conditions.

#### **Output Power**

The device has been specified for the worst-case scenario—when both inputs are in phase. Under this condition, the drivers simultaneously draw current from the charge pump, leading to a slight loss in headroom of Vss. In typical stereo audio applications, the left and right signals have differences in both magnitude and phase, subsequently leading to an increase in the maximum attainable output power. Figure 5 shows the two extreme cases for in and out of phase. In reality, the available power lies between these extremes.

#### Powering Other Circuits from a Negative Supply

An additional benefit of the MAX4411 is the internally generated, negative supply voltage (PVss). This voltage provides the ground-referenced output level. PVss can, however, also be used to power other devices within a design limit current drawn from PVss to 5mA; exceeding this affects the headphone driver operation. A typical application is a negative supply to adjust the contrast of LCD modules.

PVss is roughly proportional to PVDD and is not a regulated voltage. The charge-pump output impedance must be taken into account when powering other devices from PVss. The charge-pump output impedance plot appears in the  $Typical\ Operating\ Characteristics$ . For best results, use 2.2 $\mu$ F charge-pump capacitors.

#### **Component Selection**

#### Input Filtering

The input capacitor ( $C_{IN}$ ), in conjunction with the internal  $R_{IN}$ , forms a highpass filter that removes the DC bias from an incoming signal (see *Typical Application Circuit*). The AC-coupling capacitor allows the amplifier to bias the signal to an optimum DC level. Assuming zero-source impedance, the -3dB point of the highpass filter is given by:

$$f_{-3dB} = \frac{1}{2\pi R_{IN} C_{IN}}$$

 $R_{\mbox{\footnotesize{IN}}}$  is the amplifier's internal input resistance value given in the <code>Electrical Characteristics</code>. Choose the  $C_{\mbox{\footnotesize{IN}}}$  such that  $f_{\mbox{\footnotesize{-}3dB}}$  is well below the lowest frequency of interest. Setting  $f_{\mbox{\footnotesize{-}3dB}}$  too high affects the amplifier's low-frequency response. Use capacitors whose dielectrics have low-voltage coefficients, such as tantalum or aluminum electrolytic ones. Capacitors with high-voltage coefficients, such as ceramics, may result in increased distortion at low frequencies.

#### Charge-Pump Capacitor Selection

Use capacitors with an ESR less than  $100m\Omega$  for optimum performance. Low-ESR ceramic capacitors minimize the output resistance of the charge pump. For best performance over the extended temperature range, select capacitors with an X7R dielectric. Table 1 lists suggested manufacturers.

#### Flying Capacitor (C1)

The value of the flying capacitor (C1) affects the charge pump's load regulation and output resistance. A C1 value that is too small degrades the device's ability to provide sufficient current drive, which leads to a loss of output voltage. Increasing the value of C1 improves load regulation and reduces the charge-pump output resistance to an extent. See the Output Power vs. Charge-Pump Capacitance and Load Resistance graph in the *Typical Operating Characteristics*. Above 2.2µF, the on-resistance of the switches and the ESR of C1 and C2 dominate.

#### Hold Capacitor (C2)

The hold capacitor value and ESR directly affect the ripple at PVss. Increasing the value of C2 reduces

**Table 1. Suggested Capacitor Manufacturers** 

SUPPLIER	PHONE	FAX	WEBSITE
Taiyo Yuden	800-348-2496	847-925-0899	www.t-yuden.com
TDK	847-803-6100	847-390-4405	www.component.tdk.com

Note: Please indicate you are using the MAX4411 when contacting these component suppliers.

output ripple. Likewise, decreasing the ESR of C2 reduces both ripple and output resistance. Lower capacitance values can be used in systems with low maximum output power levels. See the Output Power vs. Charge-Pump Capacitance and Load Resistance graph in the *Typical Operating Characteristics*.

#### Power-Supply Bypass Capacitor

The power-supply bypass capacitor (C3) lowers the output impedance of the power supply, and reduces the impact of the MAX4411's charge-pump switching transients. Bypass PVDD with C3, the same value as C1, and place it physically close to the PVDD and PGND pins.

#### **Adding Volume Control**

The addition of a digital potentiometer provides simple volume control. Figure 6 shows the MAX4411 with the MAX5408 dual log taper digital potentiometer used as an input attenuator. Connect the high terminal of the MAX5408 to the audio input, the low terminal to ground, and the wiper to C<sub>IN</sub>. Setting the wiper to the top position passes the audio signal unattenuated. Setting the wiper to the lowest position fully attenuates the input.

#### **Layout and Grounding**

Proper layout and grounding are essential for optimum performance. Connect PGND and SGND together at a single point on the PC board. Connect all components associated with the charge pump (C2 and C3) to the PGND plane. Connect PVDD and SVDD together at the

device. Connect PVss and SVss together at the device. Bypassing of both supplies is accomplished by charge-pump capacitors C2 and C3 (see *Typical Application Circuit*). Place capacitors C2 and C3 as close to the device as possible. Route PGND and all traces that carry switching transients away from SGND and the traces and components in the audio signal path.

The QFN package features an exposed paddle that improves thermal efficiency of the package. However, the MAX4411 does not require additional heatsinking. Ensure that the exposed paddle is isolated from GND or Vpp. Do not connect the exposed paddle to GND or Vpp.

When using the MAX4411 in a UCSP package, make sure the traces to OUTR (bump C2) are wide enough to handle the maximum expected current flow. Multiple traces may be necessary.

### **UCSP Applications Information**

For the latest application details on UCSP construction, dimensions, tape carrier information, printed circuit board techniques, bump-pad layout, and recommended reflow temperature profile, as well as the latest information on reliability testing results, go to Maxim's website at www.maxim-ic.com/ucsp and look up the Application Note: UCSP-A Wafer-Level Chip-Scale Package.

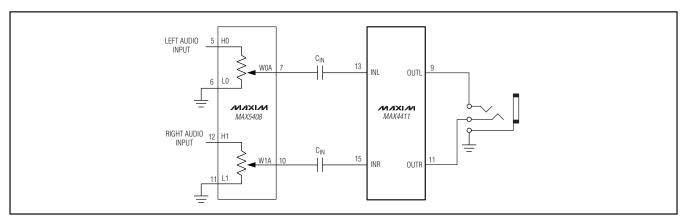
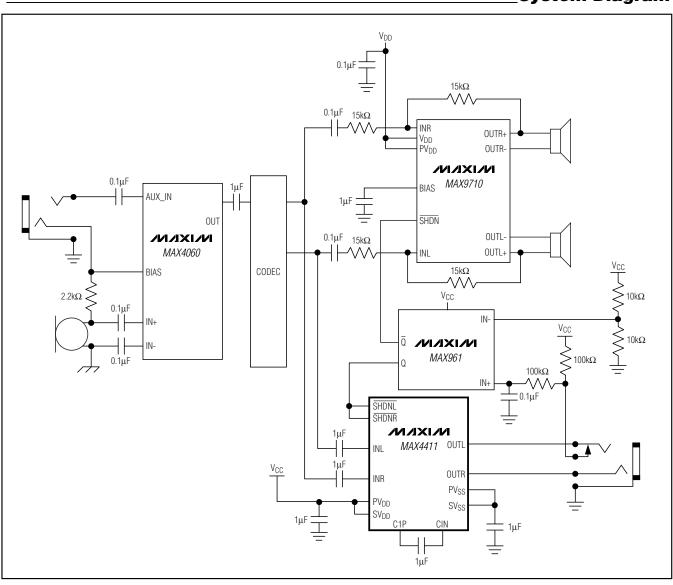
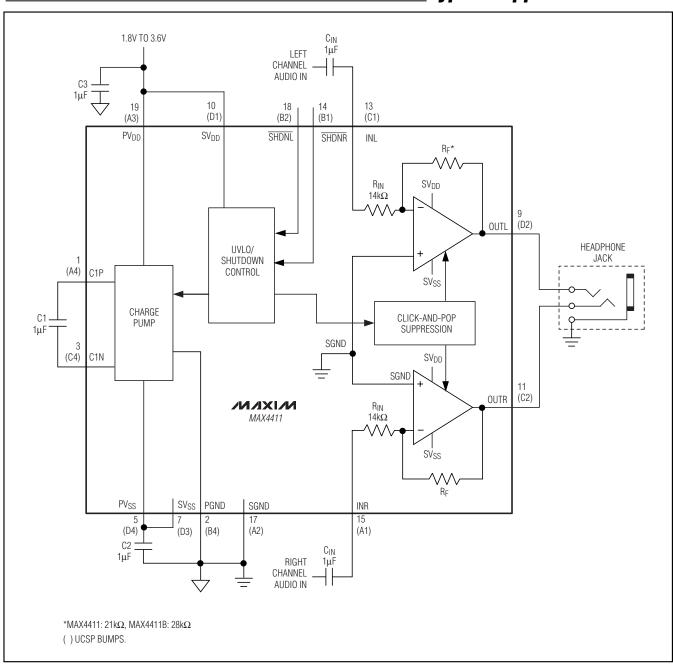


Figure 6. MAX4411 and MAX5408 Volume Control Circuit

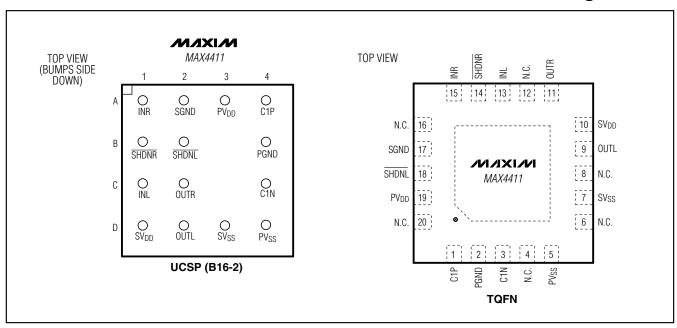
### System Diagram



## **Typical Application Circuit**



### **Pin Configurations**



## Ordering Information (continued)

PART	TEMP RANGE	PIN/BUMP- PACKAGE	GAIN (V/V)
MAX4411ETP+	-40°C to +85°C	20 Thin QFN	-1.5
MAX4411BEBE-T	-40°C to +85°C	16 UCSP-16	-2
MAX4411BEBE+T	-40°C to +85°C	16 UCSP-16	-2
MAX4411BETP	-40°C to +85°C	20 Thin QFN	-2
MAX4411BETP+	-40°C to +85°C	20 Thin QFN	-2

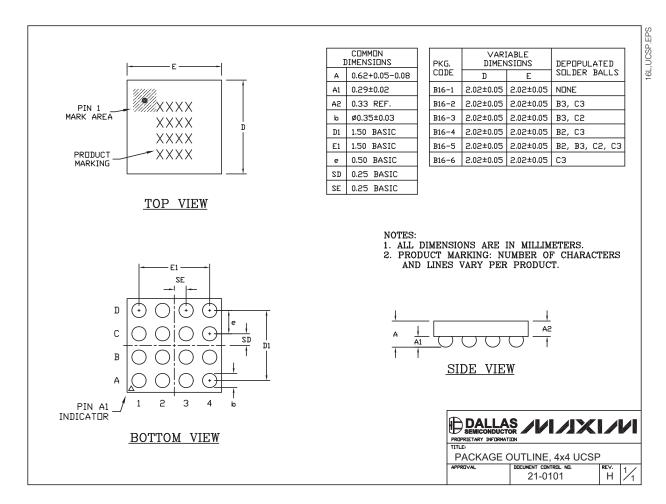
<sup>+</sup>Denotes lead-free package.

## \_Chip Information

TRANSISTOR COUNT: 4295 PROCESS: BICMOS

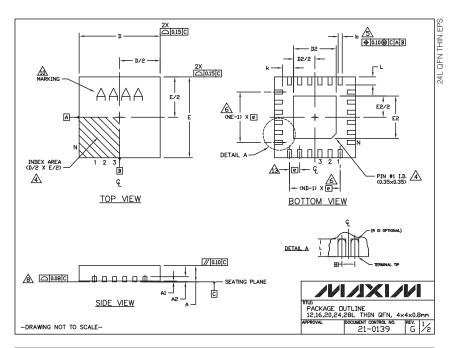
#### Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



#### Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



				CDN		DIME	ISNE	CND							1	EXP	DSEI	D PA	D V	ARIA	TION	S
PKG	12L 4			L 4×		201	4×4	4	2	4L 4×	4	28	3L 4×	۲4	]	PKG.		D2			E2	
REF.	MIN. NOM	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NDM.	MAX.	MIN.	NOM.	MAX.	]	CODES	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.
A	0.70 0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	1	T1244-3	1.95	2.10	2.25	1.95	2.10	2.25
A1	0.0 0.02		0.0		0.05	***		0.05	0.0	0.02	0.05	0.0	0.02	0.05	1	T1244-4	1.95	2.10	_	1.95	2.10	2.25
A2	0.20 F	-	-	20 RE	F	-	0 REF	7	_ 0	.20 RE	_	0.	20 RE	F	1	T1644-3	1.95	2.10	2.25	1.95	2.10	2,25
b	0.25 0.30	0.35	0.25	0.30	0.35		0.25	0.30	0.18		0.30	0.15	0.20	0.25	1	T1644-4	1.95	2.10	2.25	1.95	2.10	2,25
D	3.90 4.00	4.10	3.90	4.00	4.10		4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	1	T2044-2	1.95	2.10		1.95	2.10	2.25
E	3.90 4.00		3.90		4.10	3.90		4.10	3.90		4.10	3.90		4.10	1	T2044-3	1.95	2.10	2.25	1.95	2.10	2.25
е .	0.80			.65 BS	-		0 BSC		_	.50 BS	_	-	.40 BS	-	1	T2444-2	1.95	2.10	2.25	1.95	2.10	2.25
k	0.25 -	-	0.25	-	-	0.25	-	-	0.25	-	-	0.25	-	-	-	T2444-3	2.45	2.60	2.63	2.45	2.60	2.63
L		0.65	0.45	0.55	0.65	0.45	_	0.65	0.30	0.40	0.50	0.30	0.40	0.50	1	T2444-4	2.45	2.60	2.63	2.45	2.60	2.63
ND ND	12		$\vdash$	16	_		20 5		$\vdash$	6		├	28 7		1	T2844-1	2.50	2.60	2.70	2.50	2.60	2.70
NE NE	3	4 5 6 7		1																		
Jedec Var.	VGG		_	VGGC			GGD-1		-	WGGD-	_		VGGE		1							
	DIMENSI	ONS AF	RE IN	MILLI	METE						:S.											
THE TEF MAY	DIMENSI S THE TO TERMINATE TERMINATE THE TER	DNS AF TAL N L #1 I IDENT ER A I APPLI	RE IN UMBER DENTI IFIER MOLD ES TO	MILLI FIER ARE OR MA	METER TERMIN AND OPTION ARKED ALLIZ	RS. AND MALS. FERMIN INAL, I FEATI ED TEI	GLES AL NI BUT M JRE, RMINA	ARE UMBE UST	IN D RING BE L ID IS	CONV OCATE MEAS	ENTIO	THIN BETW	THE :	ZONE 0.25mr	INDICA n AND	JESD 95-1 ITED. THE 0.30mm FRE	TERMIN	IAL #	1 IDE	NTIFIE	R	
MAY THE MAY DIM TOF OF O	_ DIMENSI IS THE TO E TERMINA RMINAL #1 Y BE EITH IENSION b	ONS AFTAL N L #1 1 IDENT ER A   APPLI REFER N IS F APPL IFORMS FOR PA SHALL ALL NO RLINES EADS	RE IN UMBER DENTI IFIER MOLD ES TO TO TH POSSII IES TO ACKAGI L NOT TO B SHOW	MILLI OF THE ARE OR MATHE NU BLE IN OTHE JEDEC E ORI OTHE CEED E AT N ARE	IMETEI FERMII AND I ARKED ARKED ALLIZ MBER I A S EXPI MD22 ENTAT EED 0 0.10mm TRUE	RS. ANI NALS. FERMIN INAL, I FEATI ED TEI OF TE YMMETF JSED I O, EXC TON RI OBmm. I POSIT REFER	GLES AL NI BUT M JRE. RMINA RMINA RICAL BEAT EFERE	ARE UMBE AUST ALS II FAS SINK FOR ENCE AS D	IN DI RING BE L ID IS DIN EA CHION. SLUC T244 DINLY EFINE Y.	CONVOCATE MEAS CH D S AS 4-3,	ENTIO ED WI URED AND WELL T2444	THIN BETW E SID AS T 1-4 AF	THE : E RE: HE TI ND TE	ZONE  0.25mr SPECT  ERMIN 2844-	INDICA m AND FIVELY IALS. 1.	O.30mm FRE	TERMIN	IAL #:	1 IDEI	NTIFIE		

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